



ASSOCIATION CONNECTING  
ELECTRONICS INDUSTRIES®



# CALL FOR PAPERS

## 17<sup>TH</sup> SHANGHAI INTERNATIONAL SMT HIGH-LEVEL CONFERENCE

### Lead Free Manufacture Conference and Workshops

April 24-26, 2007 | Shanghai, China

**Sponsor:** China Ministry of Information Industry  
**Organizer:** CCPIT Electronics & Information Industry Sub-Council and IPC  
**Co-Organizers:** BJSMT and CBC  
**Workshop Dates:** April 24-25  
**Conference Date:** April 26, 2007  
**Venue:** Conference room # 10,  
2nd Floor Shanghai Ever Bright International Hotel

CCPIT, IPC - Association Connecting Electronics Industries, Beijing SMT and CBC are jointly organizing the 17th Shanghai International SMT High Level Conference to be held April 24-26, 2007 during NEPCON Shanghai week in Shanghai, China.

The change to Pb-free is affecting the global marketplace, motivating all suppliers and manufacturers to eliminate lead according to agreed transition plans. Producers of equipment not directly affected by the legislation e.g. aerospace are also assessing the effects of changes in the supply chain and customer demand. As global legislation continues to be implemented, companies are focusing on manufacturing, while still having some concern about long term reliability.

### PRESENTATION AND/OR PAPER SUBMISSION

Papers from environmental managers and technical experts are sought on any relevant subjects, including;

- European/Chinese/other legislation on hazardous materials and recycling
- Legislative compliance, policy enforcement and product marking
- Summary of voluntary implementation in other regions (America, China, Europe, etc.)
- Company and research consortia projects and results
- Design issues (for ease of production and disassembly)
- PCB issues (effects of lead-free process temperatures, board finishes etc)
- Component issues (effects of lead-free process temperatures, BGAs, obsolescence etc)
- New finishes (plating technology, solderability and tin whiskering)

- Comparisons of solder alloys (mainstream (e.g. SnAgCu, SnCu) and specialist (e.g. SnZnAl) compositions)
- Alternative means of substitution (conductive adhesives etc)
- Lead-free manufacturing (examples of implementation, process considerations, inspection etc)
- Repair and rework (process control, mixed alloy systems etc)
- Reliability evaluations (research, product test and in-service, including new test methods)
- Lead-free and other product sectors (automotive, aerospace etc)
- Environmental considerations and studies (material availability, toxicity issues etc)
- Recycling (examples, plans and concerns)
- Business issues (supply chains, cost – benefit analysis etc)

The conference offers 30-45 minute time slots to allow time for the presentation and discussion. Mandarin presentations preferred. English with English/Mandarin text in PowerPoint is acceptable.

Please submit 200-300 word abstracts along with the attached form and a brief biography. **The deadline for abstract submission is March 15, 2007.**

Presentation material and/or paper must be non-commercial in nature, focusing on technology rather than a company's product. It is mandatory to electronically provide copies of the presentation slides and/or technical paper for the conference proceedings.

Speakers will receive discounted admission to the conference, including a copy of proceedings, and any refreshments.

### SPONSORSHIPS AND EXHIBITS

Companies interested in event sponsorship opportunities, please contact Sally Cai +86 21 5497 3435 for more information.

### REGISTRATION INFORMATION

If you would like to be informed of registration information regarding the CCPIT, IPC - Association Connecting Electronics Industries, Beijing SMT and CBC are jointly organizing the 17th Shanghai International SMT High Level Conference when available; please send your contact details to IPCShanghai@ipc.org.



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## PROPOSED PRESENTATION

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**When complete, please fax or e-mail this form with your biography and abstract to:**

David W. Bergman, CAE

Vice President Standards, Technology and International Relations,

IPC

3000 Lakeside Drive #309S

Bannockburn, IL 60015-1249

Dir. Line +1 847-597-2840 or +86 21 5497 3435

Dir. Fax +1 847-615-5640

E-mail IPCShanghai@ipc.org or web [www.ipc.org/IPCShanghai](http://www.ipc.org/IPCShanghai)

Specific conference questions, please e-mail David Bergman at [DavidBergman@ipc.org](mailto:DavidBergman@ipc.org)

Name \_\_\_\_\_

Company \_\_\_\_\_ Title \_\_\_\_\_

Street Address \_\_\_\_\_

City \_\_\_\_\_ State/Zip Code \_\_\_\_\_

Country \_\_\_\_\_

Phone \_\_\_\_\_ Fax \_\_\_\_\_

E-mail \_\_\_\_\_

On a **separate page**, please include a paragraph-length **biography** and your 200–300 word **abstract** describing the presentation you wish to have considered for the Conference.

Presentation Title: \_\_\_\_\_

Has this paper been presented before? ☐ Yes ☐ No

If yes, when and where?

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- Abstract Submission deadline March 15, 2007
- Paper Submission due before April 9, 2007